



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-11-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MZK0*U1L3AA5	A	SH1A	2015-11-30
Amount	UoM	Unit type	ST ECOPACK Grade	
0.76	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	260	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC105)	Tin/Silver/Copper (Sn/Ag/Cu)	NAC		

Package Designator	Size	Nbr of instances	Shape	
WAFER	0.828 - 0.828 - 0.36	4	NAC	
Comment	Package: CSPS0.4 4-6, MD valid for CP:LD39030SJ15R.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MZK0*U1L3AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	0.760	mg	supplier	die	Silicon (Si)	7440-21-3		0.528	mg	694737	694737
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	5263	5263
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	3947	3947
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	1316	1316
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.008	mg	10526	10526
Die or Dies				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.005	mg	6579	6579
Die or Dies				supplier	UBM	Copper (Cu)	7440-50-8		0.003	mg	3947	3947
Die or Dies				supplier	UBM	Nickel (Ni)	7440-02-0		0.003	mg	3947	3947
Die or Dies				supplier	bump	Tin (Sn)	7440-31-5		0.202	mg	265789	265789
Die or Dies				supplier	bump	Silver (Ag)	7440-22-4		0.002	mg	2632	2632
Die or Dies				supplier	bump	Copper (Cu)	7440-50-8		0.001	mg	1316	1316